

IEEE Standard for Test Access Architecture for Three-Dimensional Stacked Integrated Circuits

IEEE Computer Society

Developed by the
Test Technology Standards Committee

IEEE 1838™-2019

STANDARDS

IEEE Standard for Test Access Architecture for Three-Dimensional Stacked Integrated Circuits

Developed by the

Test Technology Standards Committee
of the
IEEE Computer Society

Approved 7 November 2019

IEEE SA Standards Board

Abstract: IEEE Std 1838 is a die-centric standard; it applies to a die that is intended to be part of a multi-die stack. This standard defines die-level features that, when compliant dies are brought together in a stack, comprise a stack-level architecture that enables transportation of control and data signals for the test of (1) intra-die circuitry and (2) inter-die interconnects in both (a) pre-stacking and (b) post-stacking situations, the latter for both partial and complete stacks in both pre-packaging, post-packaging, and board-level situations. The primary focus of inter-die interconnect technology addressed by this standard is through-silicon vias (TSVs); however, this does not preclude its use with other interconnect technologies such as wire-bonding.

Keywords: 3D test access, flexible parallel port, FPP, IEEE 1838, multi-tower stack, primary test access port, scan, secondary test access port, test, through-silicon via, TSV

The Institute of Electrical and Electronics Engineers, Inc.
3 Park Avenue, New York, NY 10016-5997, USA

Copyright © 2020 by The Institute of Electrical and Electronics Engineers, Inc.
All rights reserved. Published 13 March 2020. Printed in the United States of America.

IEEE is a registered trademark in the U.S. Patent & Trademark Office, owned by The Institute of Electrical and Electronics Engineers, Incorporated.

PDF: ISBN 978-1-5044-6343-0 STD23997
Print: ISBN 978-1-5044-6344-7 STDPD23997

*IEEE prohibits discrimination, harassment, and bullying.
For more information, visit <https://www.ieee.org/about/corporate/governance/p9-26.html>.
No part of this publication may be reproduced in any form, in an electronic retrieval system or otherwise, without the prior written permission of the publisher.*

Important Notices and Disclaimers Concerning IEEE Standards Documents

IEEE documents are made available for use subject to important notices and legal disclaimers. These notices and disclaimers, or a reference to this page, appear in all standards and may be found under the heading “Important Notices and Disclaimers Concerning IEEE Standards Documents.” They can also be obtained on request from IEEE or viewed at <http://standards.ieee.org/ipr/disclaimers.html>.

Notice and Disclaimer of Liability Concerning the Use of IEEE Standards Documents

IEEE Standards documents (standards, recommended practices, and guides), both full-use and trial-use, are developed within IEEE Societies and the Standards Coordinating Committees of the IEEE Standards Association (“IEEE SA”) Standards Board. IEEE (“the Institute”) develops its standards through a consensus development process, approved by the American National Standards Institute (“ANSI”), which brings together volunteers representing varied viewpoints and interests to achieve the final product. IEEE Standards are documents developed through scientific, academic, and industry-based technical working groups. Volunteers in IEEE working groups are not necessarily members of the Institute and participate without compensation from IEEE. While IEEE administers the process and establishes rules to promote fairness in the consensus development process, IEEE does not independently evaluate, test, or verify the accuracy of any of the information or the soundness of any judgments contained in its standards.

IEEE Standards do not guarantee or ensure safety, security, health, or environmental protection, or ensure against interference with or from other devices or networks. Implementers and users of IEEE Standards documents are responsible for determining and complying with all appropriate safety, security, environmental, health, and interference protection practices and all applicable laws and regulations.

IEEE does not warrant or represent the accuracy or content of the material contained in its standards, and expressly disclaims all warranties (express, implied and statutory) not included in this or any other document relating to the standard, including, but not limited to, the warranties of: merchantability; fitness for a particular purpose; non-infringement; and quality, accuracy, effectiveness, currency, or completeness of material. In addition, IEEE disclaims any and all conditions relating to: results; and workmanlike effort. IEEE standards documents are supplied “AS IS” and “WITH ALL FAULTS.”

Use of an IEEE standard is wholly voluntary. The existence of an IEEE standard does not imply that there are no other ways to produce, test, measure, purchase, market, or provide other goods and services related to the scope of the IEEE standard. Furthermore, the viewpoint expressed at the time a standard is approved and issued is subject to change brought about through developments in the state of the art and comments received from users of the standard.

In publishing and making its standards available, IEEE is not suggesting or rendering professional or other services for, or on behalf of, any person or entity nor is IEEE undertaking to perform any duty owed by any other person or entity to another. Any person utilizing any IEEE Standards document, should rely upon his or her own independent judgment in the exercise of reasonable care in any given circumstances or, as appropriate, seek the advice of a competent professional in determining the appropriateness of a given IEEE standard.

IN NO EVENT SHALL IEEE BE LIABLE FOR ANY DIRECT, INDIRECT, INCIDENTAL, SPECIAL, EXEMPLARY, OR CONSEQUENTIAL DAMAGES (INCLUDING, BUT NOT LIMITED TO: PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES; LOSS OF USE, DATA, OR PROFITS; OR BUSINESS INTERRUPTION) HOWEVER CAUSED AND ON ANY THEORY OF LIABILITY, WHETHER IN CONTRACT, STRICT LIABILITY, OR TORT (INCLUDING NEGLIGENCE OR OTHERWISE) ARISING IN ANY WAY OUT OF THE PUBLICATION, USE OF, OR RELIANCE UPON ANY STANDARD, EVEN IF ADVISED OF THE POSSIBILITY OF SUCH DAMAGE AND REGARDLESS OF WHETHER SUCH DAMAGE WAS FORESEEABLE.

Translations

The IEEE consensus development process involves the review of documents in English only. In the event that an IEEE standard is translated, only the English version published by IEEE should be considered the approved IEEE standard.

Official statements

A statement, written or oral, that is not processed in accordance with the IEEE SA Standards Board Operations Manual shall not be considered or inferred to be the official position of IEEE or any of its committees and shall not be considered to be, or be relied upon as, a formal position of IEEE. At lectures, symposia, seminars, or educational courses, an individual presenting information on IEEE standards shall make it clear that his or her views should be considered the personal views of that individual rather than the formal position of IEEE.

Comments on standards

Comments for revision of IEEE Standards documents are welcome from any interested party, regardless of membership affiliation with IEEE. However, IEEE does not provide consulting information or advice pertaining to IEEE Standards documents. Suggestions for changes in documents should be in the form of a proposed change of text, together with appropriate supporting comments. Since IEEE standards represent a consensus of concerned interests, it is important that any responses to comments and questions also receive the concurrence of a balance of interests. For this reason, IEEE and the members of its societies and Standards Coordinating Committees are not able to provide an instant response to comments or questions except in those cases where the matter has previously been addressed. For the same reason, IEEE does not respond to interpretation requests. Any person who would like to participate in revisions to an IEEE standard is welcome to join the relevant IEEE working group.

Comments on standards should be submitted to the following address:

Secretary, IEEE SA Standards Board
445 Hoes Lane
Piscataway, NJ 08854 USA

Laws and regulations

Users of IEEE Standards documents should consult all applicable laws and regulations. Compliance with the provisions of any IEEE Standards document does not imply compliance to any applicable regulatory requirements. Implementers of the standard are responsible for observing or referring to the applicable regulatory requirements. IEEE does not, by the publication of its standards, intend to urge action that is not in compliance with applicable laws, and these documents may not be construed as doing so.

Copyrights

IEEE draft and approved standards are copyrighted by IEEE under US and international copyright laws. They are made available by IEEE and are adopted for a wide variety of both public and private uses. These include both use, by reference, in laws and regulations, and use in private self-regulation, standardization, and the promotion of engineering practices and methods. By making these documents available for use and adoption by public authorities and private users, IEEE does not waive any rights in copyright to the documents.

Photocopies

Subject to payment of the appropriate fee, IEEE will grant users a limited, non-exclusive license to photocopy portions of any individual standard for company or organizational internal use or individual, non-commercial use only. To arrange for payment of licensing fees, please contact Copyright Clearance Center, Customer Service, 222 Rosewood Drive, Danvers, MA 01923 USA; +1 978 750 8400. Permission to photocopy portions of any individual standard for educational classroom use can also be obtained through the Copyright Clearance Center.

Updating of IEEE Standards documents

Users of IEEE Standards documents should be aware that these documents may be superseded at any time by the issuance of new editions or may be amended from time to time through the issuance of amendments, corrigenda, or errata. An official IEEE document at any point in time consists of the current edition of the document together with any amendments, corrigenda, or errata then in effect.

Every IEEE standard is subjected to review at least every 10 years. When a document is more than 10 years old and has not undergone a revision process, it is reasonable to conclude that its contents, although still of some value, do not wholly reflect the present state of the art. Users are cautioned to check to determine that they have the latest edition of any IEEE standard.

In order to determine whether a given document is the current edition and whether it has been amended through the issuance of amendments, corrigenda, or errata, visit IEEE Xplore at <http://ieeexplore.ieee.org/> or contact IEEE at the address listed previously. For more information about the IEEE SA or IEEE's standards development process, visit the IEEE SA Website at <http://standards.ieee.org>.

Errata

Errata, if any, for IEEE standards can be accessed via <https://standards.ieee.org/standard/index.html>. Search for standard number and year of approval to access the web page of the published standard. Errata links are located under the Additional Resources Details section. Errata are also available in IEEE Xplore: <https://ieeexplore.ieee.org/browse/standards/collection/ieee/>. Users are encouraged to periodically check for errata.

Patents

Attention is called to the possibility that implementation of this standard may require use of subject matter covered by patent rights. By publication of this standard, no position is taken by the IEEE with respect to the existence or validity of any patent rights in connection therewith. If a patent holder or patent applicant has filed a statement of assurance via an Accepted Letter of Assurance, then the statement is listed on the IEEE SA Website at <https://standards.ieee.org/about/sasb/patcom/patents.html>. Letters of Assurance may indicate whether the Submitter is willing or unwilling to grant licenses under patent rights without compensation or under reasonable rates, with reasonable terms and conditions that are demonstrably free of any unfair discrimination to applicants desiring to obtain such licenses.

Essential Patent Claims may exist for which a Letter of Assurance has not been received. The IEEE is not responsible for identifying Essential Patent Claims for which a license may be required, for conducting inquiries into the legal validity or scope of Patents Claims, or determining whether any licensing terms or conditions provided in connection with submission of a Letter of Assurance, if any, or in any licensing agreements are reasonable or non-discriminatory. Users of this standard are expressly advised that determination of the validity of any patent rights, and the risk of infringement of such rights, is entirely their own responsibility. Further information may be obtained from the IEEE Standards Association.

Participants

At the time this IEEE standard was completed, the 3D Test Working Group had the following membership:

Adam Cron, *Chair*
Erik Jan Marinissen, *Vice Chair*
Michael G. Wahl, *Editor*
Eric Cormack, *Secretary*

Saman Adham
Sandeep Bhatia
Tapan Chakraborty
Jonathon E. Colburn
Jean-Francois Cote
Alfred Crouch
Heiko Ehrenberg
Sandeep Goel

Saurabh Gupta
Jon Haldorson
Gurgen Harutyunyan
Shuichi Kameyama
Harry Linzer
Teresa McLaurin
Sophocles Metsis
Seetal Potluri
Etienne Racine

Gunasekaran
Ramasamy
Mike Ricchetti
A. T. Siyaram
Naveen Kumar
Srivastava
Craig Stephan
Min-Jer Wang

Previous members of the 3D Test Technology working group are:

Vincent Chalendar
Chen-An Chen
Vivek Chickermane
C. J. Clark
Zoe Conroy
Damon Domke
Ted Eaton
William Eklow
Tom Heilmann

Michael Higgins
Chun-Lung Hsu
Marc Hutner
Hongshin Jun
Shuichi Kameyama
Rakesh Kinger
Amit Majumdar
T.M. Mak
Arie Margulis

Benoit Nadeau-Dostie
Christos Papameletis
Ben Rogel
Francisco Russi
Ifthikhar Soomro
Brian Turmelle
Bill Tuthill
Lee Whetsel
Jae Wu

The following members of the individual Standards Association balloting group voted on this standard. Balloters may have voted for approval, disapproval, or abstention.

Saman Adham
Ken-Ichi Anzou
Sandeep Bhatia
Bill Brown
Demetrio Bucaneg Jr
Tapan Chakraborty
Jonathon E. Colburn
Eric Cormack
Jean-Francois Cote
Adam Cron
Alfred Crouch

Heiko Ehrenberg
Peter van den Eijnden
Randall Groves
Jon Haldorson
Peter Harrod
Gurgen Harutyunyan
Werner Hoelzl
Michael Laisne
Philippe Lebourg
Adam Ley

Erik Jan Marinissen
Benoit Nadeau-Dostie
Mike Ricchetti
Anthony Sparks
Naveen Srivastava
Jon Charles Stewart
Walter Struppler
Srinivasa Vemuru
Michael G. Wahl
Lisa Ward
Karl Weber

When the IEEE SA Standards Board approved this standard on 7 November 2019, it had the following membership:

Gary Hoffman, *Chair*
Ted Burse, *Vice Chair*
Jean-Philippe Faure, *Past Chair*
Konstantinos Karachalios, *Secretary*

Masayuki Ariyoshi
Stephen D. Dukes
J. Travis Griffith
Guido Hiertz
Christel Hunter
Joseph L. Koepfinger*
Thomas Koshy
John D. Kulick

David J. Law
Joseph Levy
Howard Li
Xiaohui Liu
Kevin Lu
Daleep Mohla
Andrew Myles

Annette D. Reilly
Dorothy Stanley
Sha Wei
Phil Wennblom
Philip Winston
Howard Wolfman
Feng Wu
Jingyi Zhou

*Member Emeritus

Introduction

This introduction is not part of IEEE Std 1838-2019, IEEE Standard for Test Access Architecture for Three-Dimensional Stacked Integrated Circuits.

Advancements in interconnect, assembly, and packaging technology have lead to a wide range of multi-die stack architectures. These die stacks need to be tested before they can be shipped with acceptable quality levels to customers. Consequently, three-dimensional design-for test (3D-DfT) structures that provide test access between the external stack I/Os and the various dies and inter-die interconnect are needed. Test access is needed for manufacturing phases that include both partially assembled and complete stacks. This standard addresses these issues.

Copyright OVER

Contents

1. Overview	13
1.1 Scope	13
1.2 Three-dimensional integrated circuits (ICs) stacking technology	14
1.3 Motivation for a 3D-DfT standard	15
1.4 Context	15
1.5 Organization of the standard	15
1.6 Word usage	16
2. Normative references	16
3. Definitions, acronyms, and abbreviations	16
3.1 Definitions	16
3.2 Acronyms and abbreviations	21
4. Technology	23
4.1 Stack model	23
4.2 Wafer-level die access	24
4.3 Physical attributes	25
5. Serial test access ports	26
5.1 Primary test access port	26
5.2 Primary test access port controller	28
5.3 Secondary test access port (STAP)	30
5.4 Secondary test access port control logic	31
5.5 Registers	35
5.6 Configuration elements	41
6. Die wrapper register	42
6.1 Register design	42
6.2 DWR cell structure and operation	47
6.3 DWR operation events	48
6.4 DWR operation modes	49
6.5 Parallel access to the DWR	51
6.6 DWR cell naming	52
6.7 DWR cell examples	53
6.8 Wrapper states	56
7. Flexible parallel port	57
7.1 General introduction	57
7.2 FPP lane examples	60
7.3 Structure of the FPP	62
7.4 Allocation of FPP configuration elements to the FPP lane control terminals	66
8. IEEE Std 1838 DWR relationship with other standards	66
Annex A (informative) Bubble diagrams	68
Annex B (informative) Bibliography	70